

re the Application of:

Coyle, et al.

Serial No.: 09/992,387

Filed:

For:

11/16/01

TI-31794

Docket No.:

Examiner: Lewis, Monic

Art Unit:

2822

Flip-Chip on Film Assembly for Ball Grid Array Packages

Response to Notice of Non-Compliant Amendment

Assistant Commissioner of Patents Washington, DC 20231

MAILING CERTIFICATE UNDER 37 C.F.R. §1.8(A)

I hereby certify that this correspondence is being deposited with the U.S. Postal Service as First Class Mail in an envelope addressed to: Assistant Commissioner for Patents, Washington, D.C. 20231 on

Elizabeth Austin

Dear Sir:

The following remarks are offered in response to the Notice of Non-Compliant Amendment dated 11/4/02. They are respectfully submitted as a full and complete response to that Notice. The Commissioner is hereby requested and authorized to charge any fees necessary for the filing of the enclosed papers to deposit account number 20-0668 of Texas Instruments Incorporated.

In the subject Notice, the words "not pages" were inserted by the PTO under the lines "1. A clean version of the replacement paragraph(s)/section(s) is required" and "2. A marked-up version of the replacement paragraph(s)/section(s) is required." Applicant's attorney telephoned Legal Instruments Examiner Tina M. Bell for clarification of the "not pages" insertion.

Examiner Bell informed Applicant's attorney that only clean and marked-up versions of paragraphs of the specification were permitted in an amendment. Applicant's amendment filed on 10/18/02 included more than paragraphs, which explains Examiner Bell's insertion of the words "not pages" on the form. However, as Applicant pointed out to Examiner Bell in the telephone conversation, clean and marked-up versions of sections of the specification are allowed under 37 CFR 1.121(b)(2)(ii) and 37 CFR 1.121(b)(2)(iii). Applicant's 10/18/02 amendment provides clean and marked-up sections and is therefore compliant with the relevant regulations. Applicant therefore requests reconsideration of the findings set forth in the subject Notice. Applicant is resubmitting the 10/18/02 amendment herewith with minor modifications regarding instructions for deletion and replacement of the relevant sections of the specification to ensure compliance with 37 CFR 1.121(b)(2)(i). No other changes to the 10/18/02 amendment have been made.

Applicant requests that the Examiner contact Applicant's attorney at the below listed telephone number and address should any further questions arise as to this matter.

Respectfully submitted,

Texas Instruments Incorporated P.O. Box 655474, M/S 3999

Dallas, TX 75265

Phone: 972 917-5653 Fax: 972 917-4418 Reg. No. 36,682

Michael K. Skrehot



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re the Application of:

Coyle, et al.

09/992.387 Serial No.:

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2822

For:

Flip-Chip on Film Assembly for Ball Grid Array Packages

Supplemental Amendment under 37 CFR 1.111

Assistant Commissioner of Patents Washington, DC 20231

MAILING CERTIFICATE UNDER 37 C.F.R. §1.8(A)

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Elizabeth Austin

Dear Sir:

The following amendments and remarks are offered in response to the Examiner's Office Action dated 06/20/02 and in response to the Notice of Non-Compliant Amendment dated 11/04/02. They are respectfully submitted as a full and complete response to that Action. The Commissioner is hereby requested and authorized to charge any fees necessary for the filing of the enclosed papers to deposit account number 20-0668 of Texas Instruments Incorporated.